

an encapsulant at least partially filling the cavity.

19. (Amended) The electronic package of claim 18, wherein the interposer [has a thickness less than 1 mm] the electronic component is a capacitor and the interposer is thin enough to minimize inductive loop between the capacitor and the die.

### REMARKS

Applicant has carefully reviewed and considered the Office Action mailed on December 18, 2002, and the references cited therewith. Claims 7, 15 and 17-19 are amended and claim 14 is canceled; as a result, claims 7-13 and 15-20 are now pending in this application. The amendments to the claims are supported at page 5, lines 3-18 of Applicant's specification (among other places).

### Examiner Interview

Applicant's attorney would like to thank Examiner Ori Nadav for his courtesy during the telephone interview held on February 12, 2003. Examiner Nadav discussed the scope of the amended claims with Applicant's attorney and indicated that the amended claims may overcome the cited references.

As requested by the Examiner during the interview, Applicant hereby respectfully directs the Examiner attention to Applicant's specification at page 4, lines 18-20 and page 5, lines 1-18, 25 to show the criticality of "the interposer having a thickness less than 1 mm" and "the interposer being thin enough such that the interposer is incapable of withstanding a mechanical load generated by the die and the pin carrier to an identical electronic package" as recited in amended claims 7, 15 and 18.

### §102 & 103 Rejections of the Claims

- I. Claims 7 and 18 were rejected under 35 USC § 102(b) as being anticipated by Saito et al. (U.S. Patent No. 5,570,274).

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

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- II. Claims 8-17 and 19-20 were rejected under 35 USC § 103(a) as being unpatentable over Saito et al. (U.S. Patent No. 5,570,274) in view of Applicants Admitted Prior Art (AAPA).
- III. Claims 7-20 were rejected under 35 USC § 103(a) as being unpatentable over Applicants Admitted Prior Art (AAPA) in view of Saito et al. (U.S. Patent No. 5,570,274) and Dibene, II et al. (U.S. Patent No. 6,452,113).

As discussed during interview, claims 7-13 and 15-20 as amended overcome the above pending §102 & 103 rejections. Reconsideration and allowance of claims 7-13 and 15-20 are respectfully requested.

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney Andrew Peret at 262/646-7009 or the below signed attorney to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,  
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 14 day of March 2003.

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